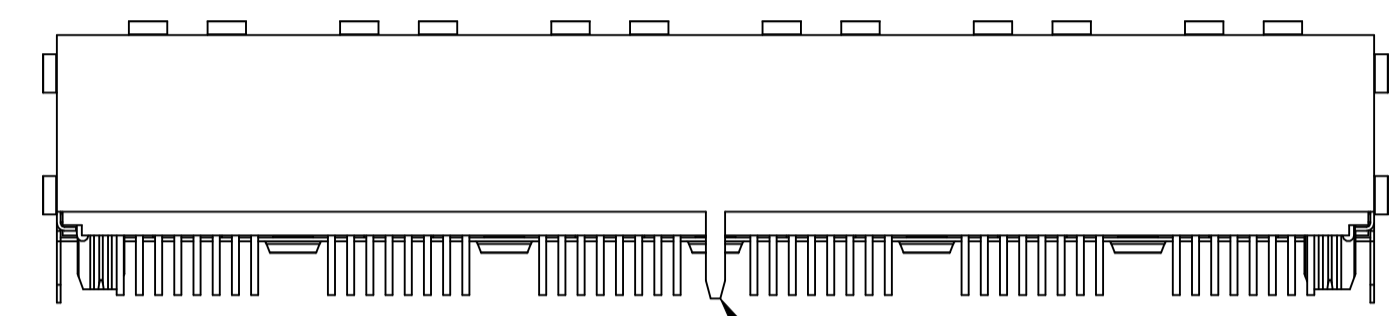
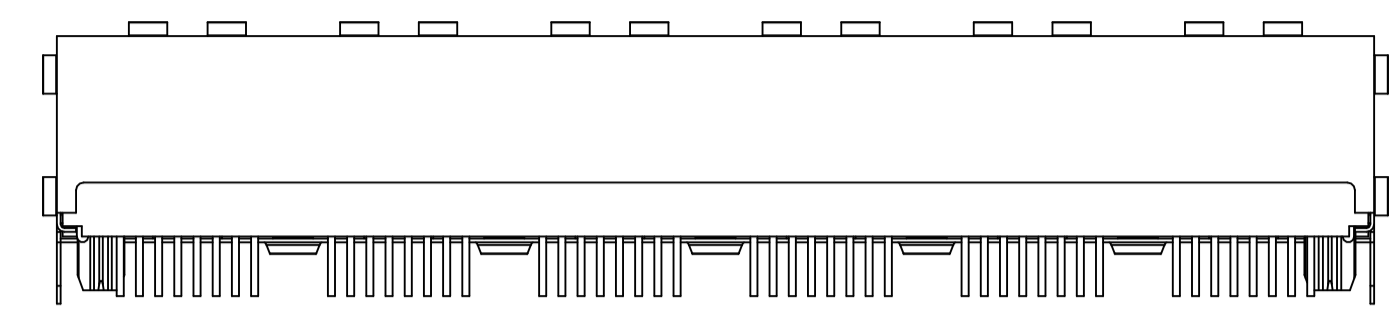
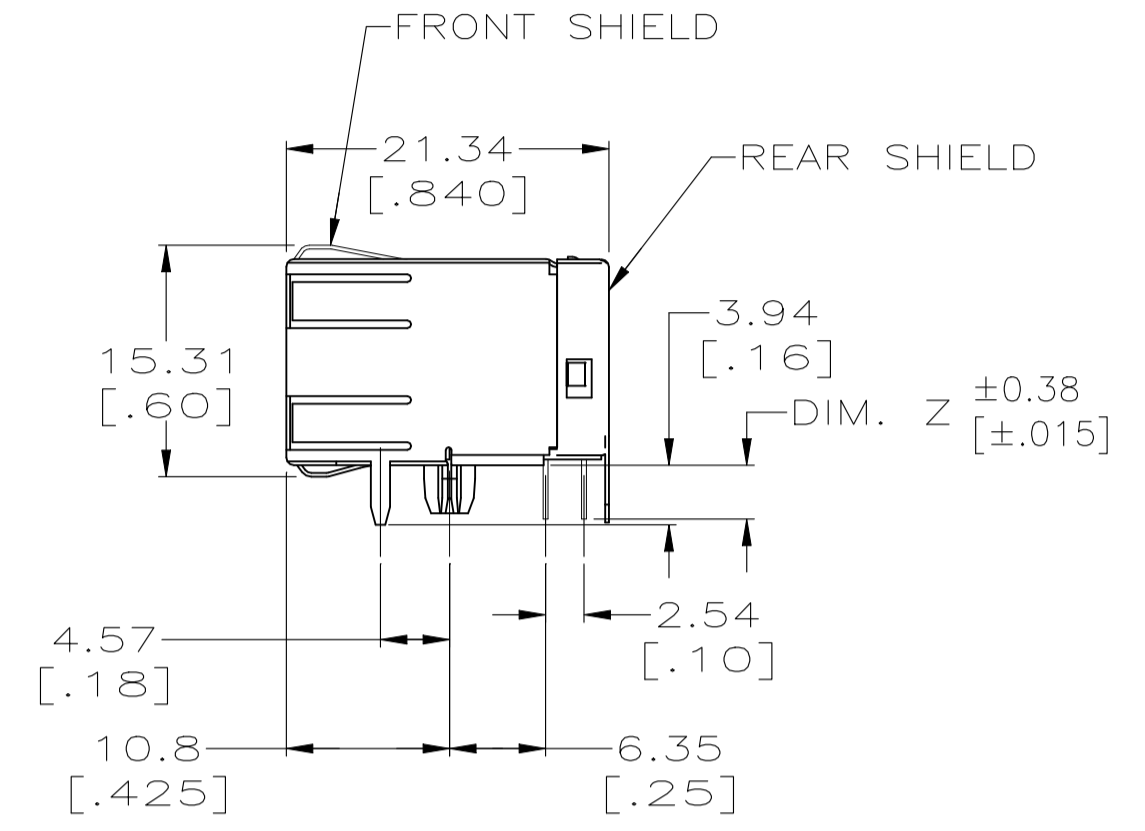
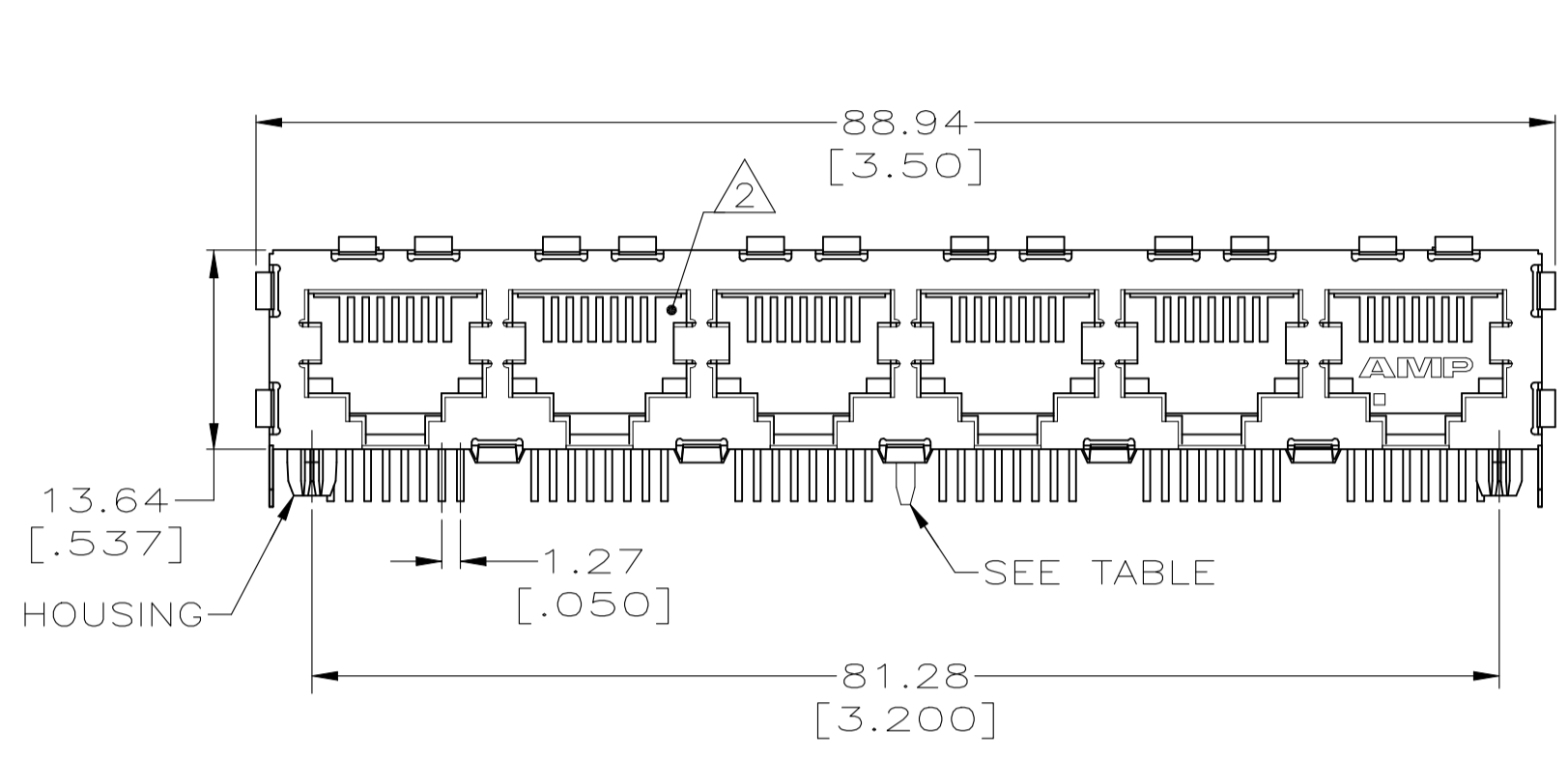


REVISIONS					
REV	DESCRIPTION	DATE	BY	APPD	
E1	ECR-19-014657	13DEC2020	RR	SZ	



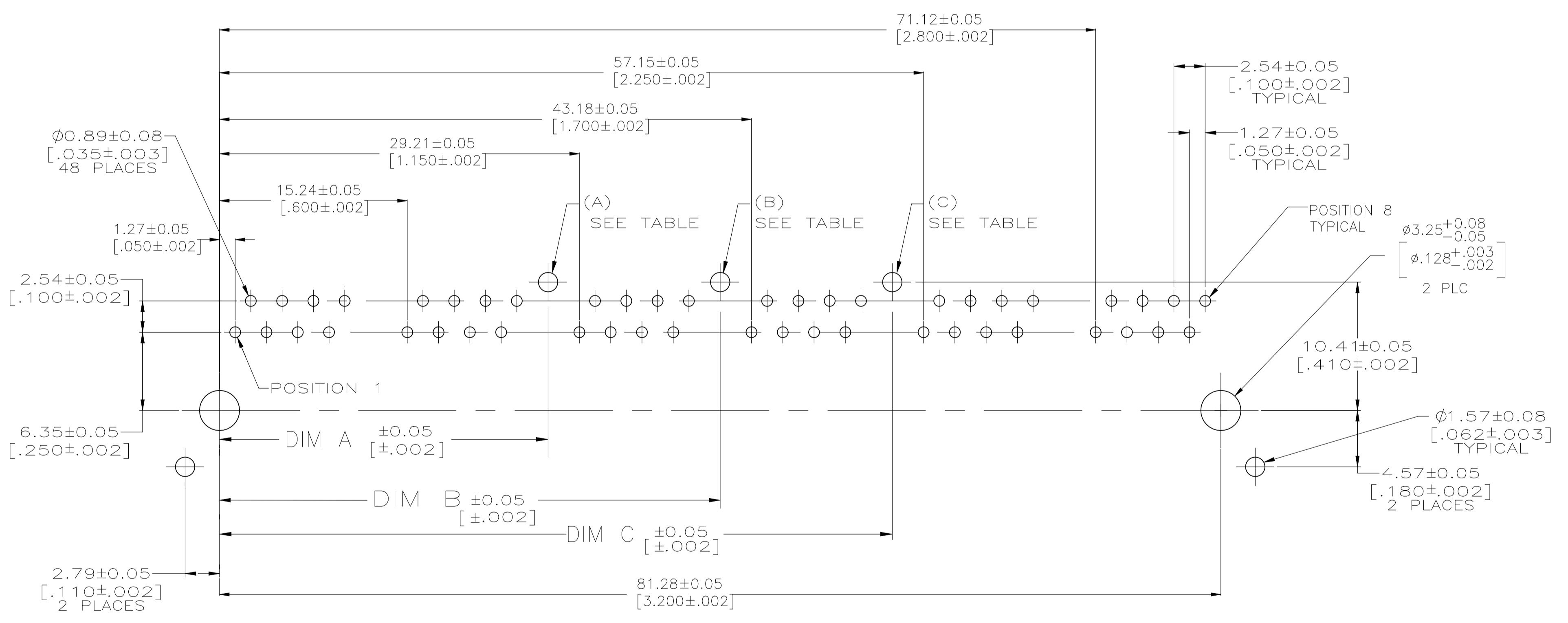
△ MATERIAL: HOUSING - NYLON, BLACK, UL 94V-0. OVERMOLDED TERMINAL ARRAY - PBT, BROWN. TERMINALS - 0.33[.013] THICK PHOS BRONZE PLATED WITH 1.27 μm[.000050] MINIMUM HARD GOLD IN LOCALIZED AREA AND 3.81 μm[.000150] MINIMUM MATTE TIN IN SOLDER AREA OVER 1.27 μm[.000050] MINIMUM NICKEL UNDERPLATE. SHIELDS - 0.25 [.010] THICK COPPER ALLOY PLATED WITH 1.27 μm[.000050] MINIMUM NICKEL AND 2.03 μm[.000080] MINIMUM HOT TIN DIP ON PCB GROUND TABS.

△ JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68 SUBPART F.

△ OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI

△ ENLARGED THE DISTANCE BETWEEN THE CONTACTS AND SHIELD

△ MATERIAL: HOUSING - NYLON, BLACK, UL 94V-0. OVERMOLDED TERMINAL ARRAY - PBT, BROWN. TERMINALS - 0.33[.013] THICK PHOS BRONZE PLATED WITH 0.76 μm[.000030] MINIMUM HARD GOLD IN LOCALIZED AREA AND 3.81 μm[.000150] MINIMUM MATTE TIN IN SOLDER AREA OVER 1.27 μm[.000050] MINIMUM NICKEL UNDERPLATE. SHIELDS - 0.25 [.010] THICK COPPER ALLOY PLATED WITH 1.27 μm[.000050] MINIMUM NICKEL AND 2.03 μm[.000080] MINIMUM HOT TIN DIP ON PCB GROUND TABS.



RECOMMENDED PC BOARD LAYOUT COMPONENT SIDE (TOP) SCALE 4:1

REV	DESCRIPTION	DATE	BY	APPD	
3	OBSOLETE	3.56 [.140]	NA	40.64 [1.600]	54.61 [2.150]
2		3.56 [.140]	NA	40.64 [1.600]	NA
1		3.56 [.140]	NA	40.64 [1.600]	NA
0		3.56 [.140]	NA	40.64 [1.600]	NA

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm [INCHES]

TOLERANCES UNLESS OTHERWISE SPECIFIED:

0 PLC	± -
1 PLC	± -
2 PLC	± 0.25[.01]
3 PLC	± 0.13[.005]
4 PLC	± -

FINISH: SEE NOTE 1

DATE: 25MAY2005

BY: T. SPRINKLE / A. MAYER

CHK: J. WESTMAN

APPD: S. FLICKINGER

NAME: MODULAR JACK ASSY, 6 PORT, 8 POSN, SHIELDED, REVERSE PANEL GROUND TABS, CAT 5e

PRODUCT SPEC: 108-1163-2

APPLICATION SPEC: 114-2048

WEIGHT: 0.000000

CAGE CODE: 114-2048

DRAWING NO: 5406206

SCALE: 2:1

SHEET: 1 of 1

REV: E1